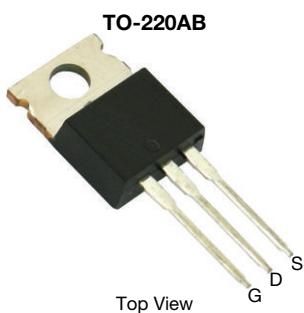


N-Channel 150 V (D-S) MOSFET

PRODUCT SUMMARY			
V_{DS} (V)	$R_{DS(on)}$ (Ω) MAX.	I_D (A)	Q_g (TYP.)
150	0.0094 at $V_{GS} = 10$ V	128	63 nC
	0.0110 at $V_{GS} = 7.5$ V	119	


Ordering Information:

SUP80090E-GE3 (lead (Pb)-free and halogen-free)

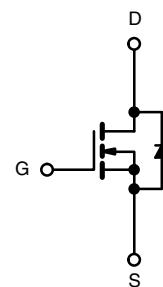
FEATURES

- ThunderFET® power MOSFET
- Maximum 175 °C junction temperature
- 100 % R_g and UIS tested
- Material categorization:
for definitions of compliance please see
www.vishay.com/doc?99912


RoHS
COMPLIANT
HALOGEN
FREE

APPLICATIONS

- Power supplies:
 - Uninterruptible power supplies
 - AC/DC switch-mode power supplies
 - Lighting
- Synchronous rectification
- DC/DC converter
- Motor drive switch
- DC/AC inverter
- Solar micro inverter
- Class D audio amplifier



N-Channel MOSFET

ABSOLUTE MAXIMUM RATINGS ($T_C = 25$ °C, unless otherwise noted)			
PARAMETER	SYMBOL	LIMIT	UNIT
Drain-Source Voltage	V_{DS}	150	V
Gate-Source Voltage	V_{GS}	± 20	
Continuous Drain Current ($T_J = 150$ °C)	$I_C = 25$ °C	128	A
	$T_C = 125$ °C	74	
Pulsed Drain Current ($t = 100$ μ s)	I_{DM}	240	
Avalanche Current	I_{AS}	60	
Single Avalanche Energy ^a	E_{AS}	180	mJ
Maximum Power Dissipation ^a	$T_C = 25$ °C	375 ^b	W
	$T_C = 125$ °C	125 ^b	
Operating Junction and Storage Temperature Range	T_J, T_{stg}	-55 to +175	°C

THERMAL RESISTANCE RATINGS			
PARAMETER	SYMBOL	LIMIT	UNIT
Junction-to-Ambient (PCB Mount) ^c	R_{thJA}	40	°C/W
Junction-to-Case (Drain)	R_{thJC}	0.4	

Notes

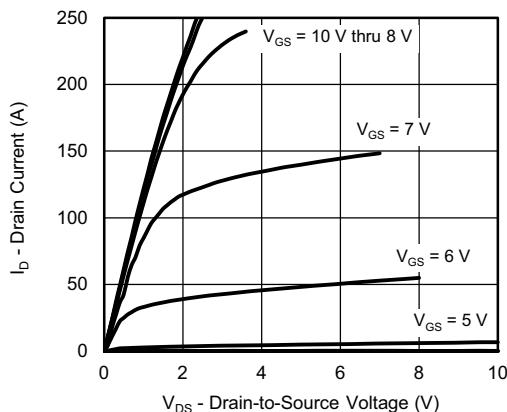
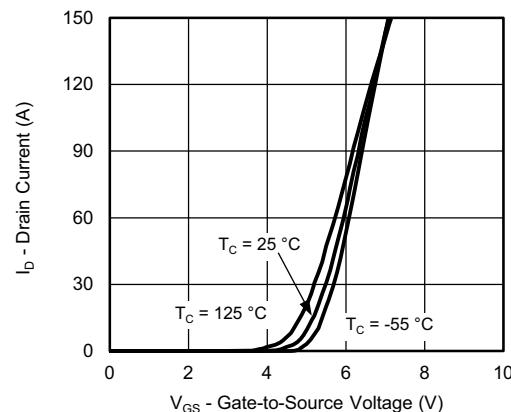
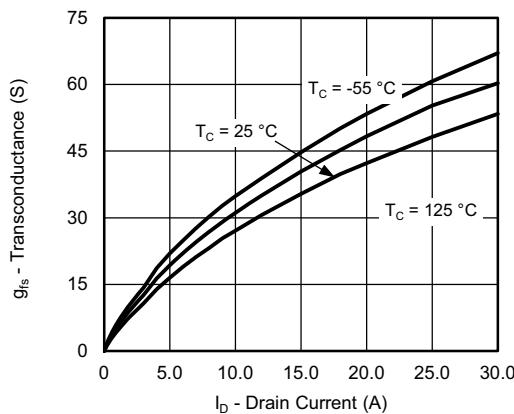
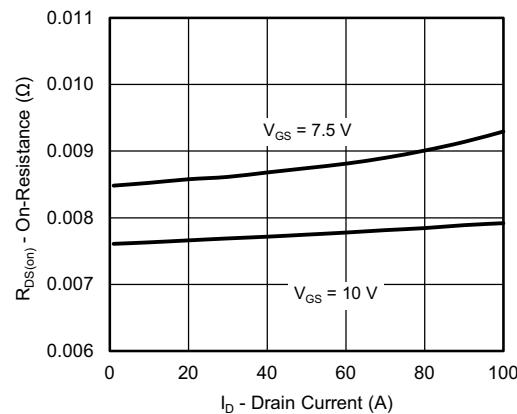
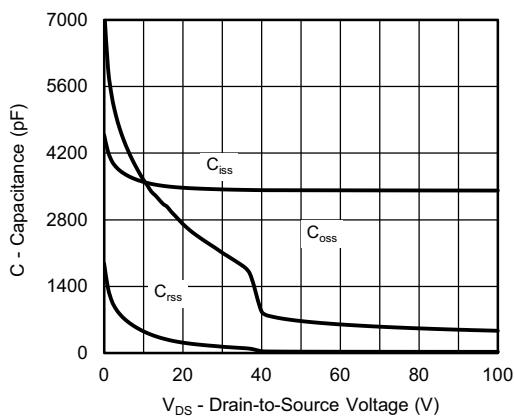
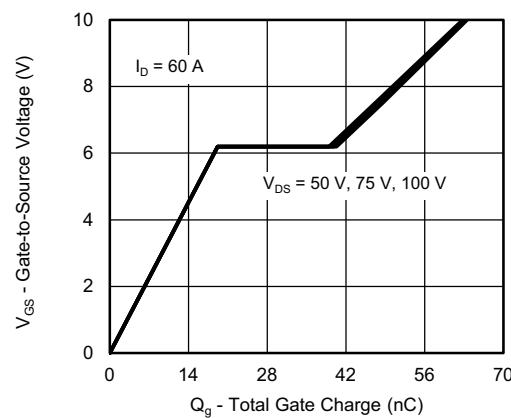
- Duty cycle ≤ 1 %.
- See SOA curve for voltage derating.
- When mounted on 1" square PCB (FR4 material).

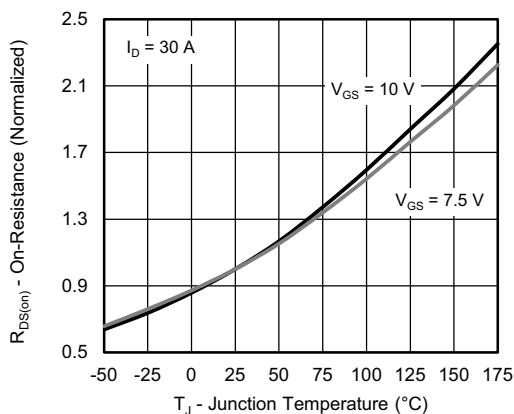
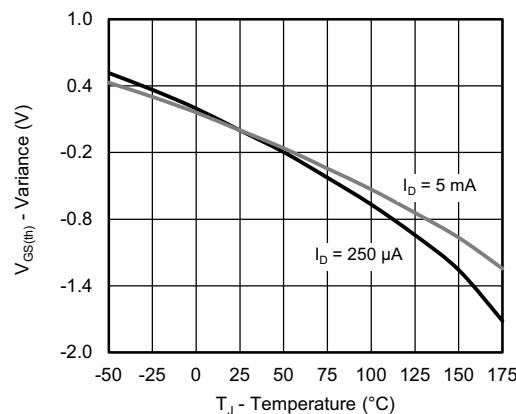
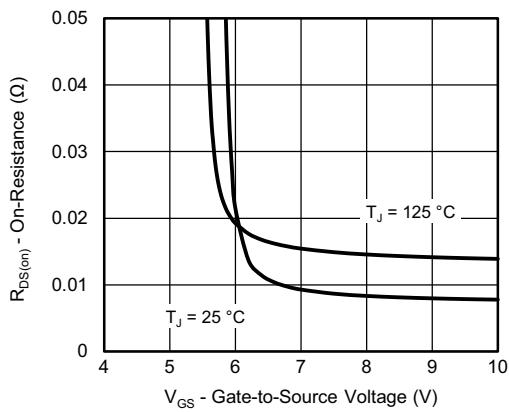
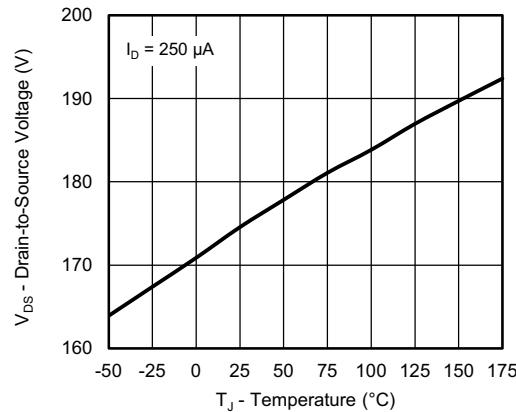
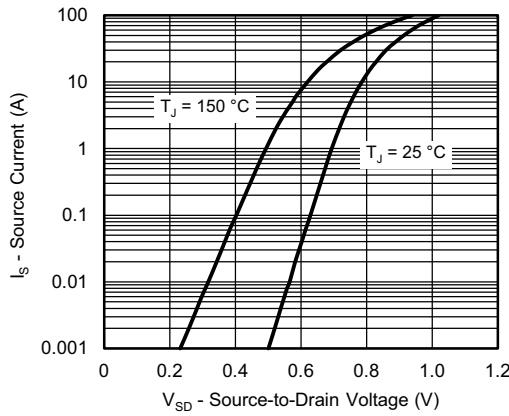
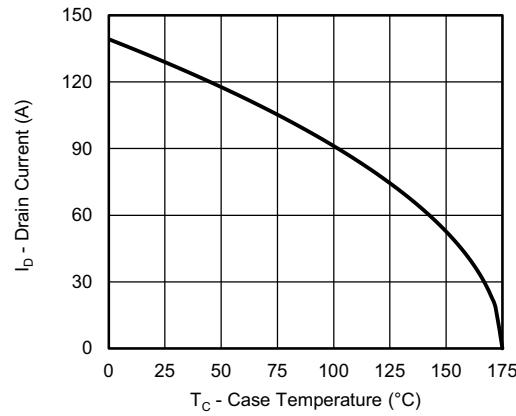
SPECIFICATIONS ($T_J = 25^\circ\text{C}$, unless otherwise noted)						
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNIT
Static						
Drain-Source Breakdown Voltage	V_{DS}	$V_{GS} = 0 \text{ V}$, $I_D = 250 \mu\text{A}$	150	-	-	V
Gate Threshold Voltage	$V_{GS(\text{th})}$	$V_{DS} = V_{GS}$, $I_D = 250 \mu\text{A}$	2	-	5	
Gate-Body Leakage	I_{GSS}	$V_{DS} = 0 \text{ V}$, $V_{GS} = \pm 20 \text{ V}$	-	-	± 250	nA
Zero Gate Voltage Drain Current	I_{DSS}	$V_{DS} = 150 \text{ V}$, $V_{GS} = 0 \text{ V}$	-	-	1	μA
		$V_{DS} = 150 \text{ V}$, $V_{GS} = 0 \text{ V}$, $T_J = 125^\circ\text{C}$	-	-	100	
		$V_{DS} = 150 \text{ V}$, $V_{GS} = 0 \text{ V}$, $T_J = 175^\circ\text{C}$	-	-	2	mA
On-State Drain Current ^a	$I_{D(\text{on})}$	$V_{DS} \geq 10 \text{ V}$, $V_{GS} = 10 \text{ V}$	90	-	-	A
Drain-Source On-State Resistance ^a	$R_{DS(\text{on})}$	$V_{GS} = 10 \text{ V}$, $I_D = 30 \text{ A}$	-	0.0078	0.0094	Ω
		$V_{GS} = 7.5 \text{ V}$, $I_D = 30 \text{ A}$	-	0.0087	0.0110	
Forward Transconductance ^a	g_{fs}	$V_{DS} = 15 \text{ V}$, $I_D = 30 \text{ A}$	-	52	-	S
Dynamic ^b						
Input Capacitance	C_{iss}	$V_{GS} = 0 \text{ V}$, $V_{DS} = 75 \text{ V}$, $f = 1 \text{ MHz}$	-	3425	-	pF
Output Capacitance	C_{oss}		-	535	-	
Reverse Transfer Capacitance	C_{rss}		-	26	-	
Total Gate Charge ^c	Q_g	$V_{DS} = 75 \text{ V}$, $V_{GS} = 10 \text{ V}$, $I_D = 60 \text{ A}$	-	63	95	nC
Gate-Source Charge ^c	Q_{gs}		-	19.5	-	
Gate-Drain Charge ^c	Q_{gd}		-	20.5	-	
Gate Resistance	R_g	$f = 1 \text{ MHz}$	1.5	3	5	Ω
Turn-On Delay Time ^c	$t_{d(\text{on})}$	$V_{DD} = 75 \text{ V}$, $R_L = 1.25 \Omega$ $I_D \geq 60 \text{ A}$, $V_{GEN} = 10 \text{ V}$, $R_g = 1 \Omega$	-	15	30	ns
Rise Time ^c	t_r		-	114	220	
Turn-Off Delay Time ^c	$t_{d(\text{off})}$		-	28	56	
Fall Time ^c	t_f		-	8	16	
Drain-Source Body Diode Ratings and Characteristics ^b ($T_C = 25^\circ\text{C}$)						
Pulsed Current ($t = 100 \mu\text{s}$)	I_{SM}		-	-	240	A
Forward Voltage ^a	V_{SD}	$I_F = 30 \text{ A}$, $V_{GS} = 0 \text{ V}$	-	0.73	1.2	V
Reverse Recovery Time	t_{rr}	$I_F = 30 \text{ A}$, $\text{di}/\text{dt} = 100 \text{ A}/\mu\text{s}$	-	110	220	ns
Peak Reverse Recovery Charge	$I_{RM(\text{REC})}$		-	10	20	A
Reverse Recovery Charge	Q_{rr}		-	0.5	1	μC

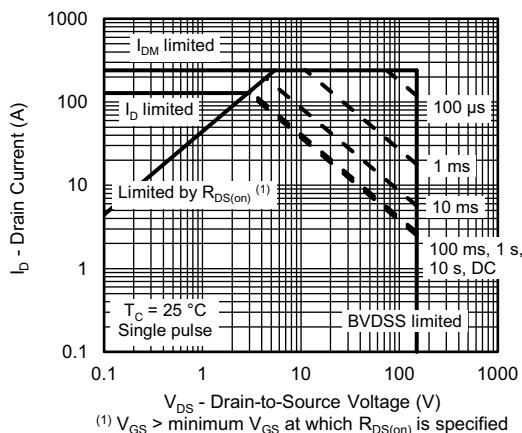
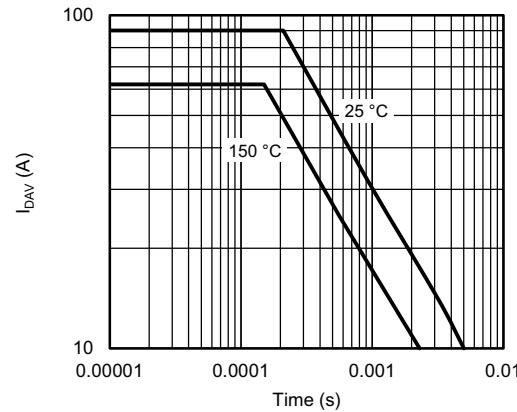
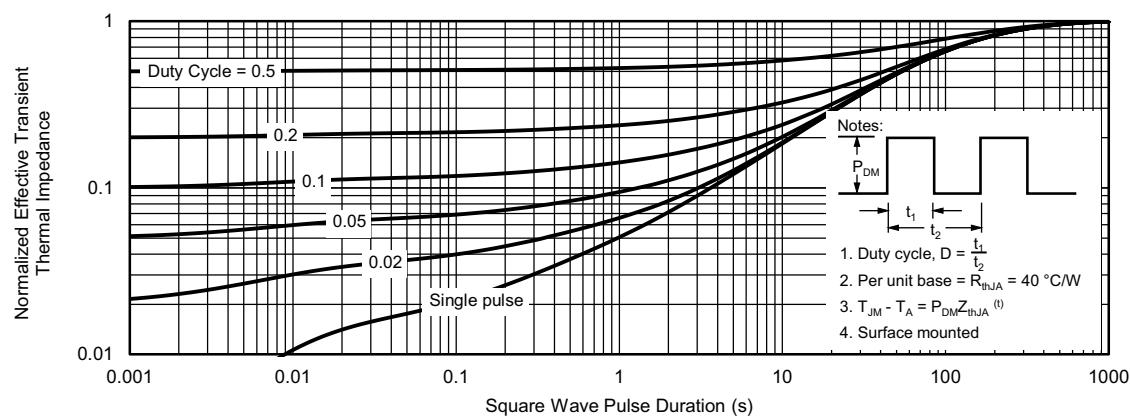
Notes

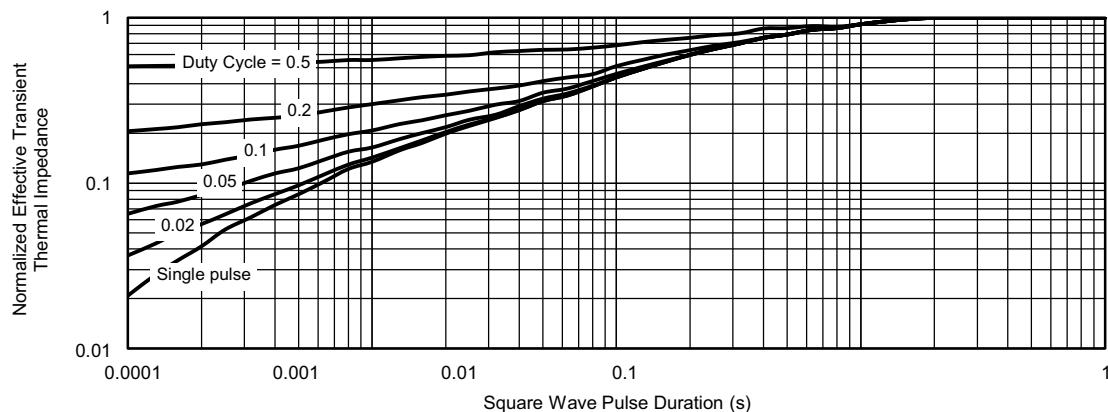
- Pulse test; pulse width $\leq 300 \mu\text{s}$, duty cycle $\leq 2 \%$.
- Guaranteed by design, not subject to production testing.
- Independent of operating temperature.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

TYPICAL CHARACTERISTICS ($T_A = 25^\circ\text{C}$, unless otherwise noted)

Output Characteristics

Transfer Characteristics

Transconductance

On-Resistance vs. Drain Current

Capacitance

Gate Charge

TYPICAL CHARACTERISTICS ($T_A = 25^\circ\text{C}$, unless otherwise noted)

On-Resistance vs. Junction Temperature

Threshold Voltage

On-Resistance vs. Gate-to-Source Voltage

Drain Source Breakdown vs. Junction Temperature

Source Drain Diode Forward Voltage

Current De-Rating

THERMAL RATINGS ($T_A = 25^\circ\text{C}$, unless otherwise noted)

Safe Operating Area

 I_{DAV} vs. Time

Normalized Thermal Transient Impedance, Junction-to-Ambient

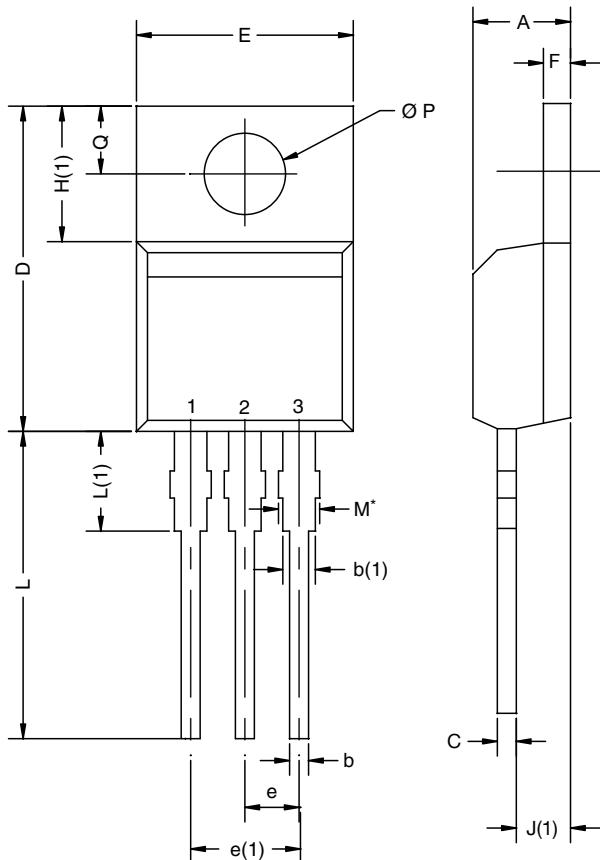
THERMAL RATINGS ($T_A = 25^\circ\text{C}$, unless otherwise noted)

Normalized Thermal Transient Impedance, Junction-to-Case
Note

- The characteristics shown in the two graphs
 - Normalized Transient Thermal Impedance Junction to Ambient (25°C)
 - Normalized Transient Thermal Impedance Junction to Case (25°C)

are given for general guidelines only to enable the user to get a "ball park" indication of part capabilities. The data are extracted from single pulse transient thermal impedance characteristics which are developed from empirical measurements. The latter is valid for the part mounted on printed circuit board - FR4, size 1" x 1" x 0.062", double sided with 2 oz. copper, 100 % on both sides. The part capabilities can widely vary depending on actual application parameters and operating conditions.

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TO-220AB

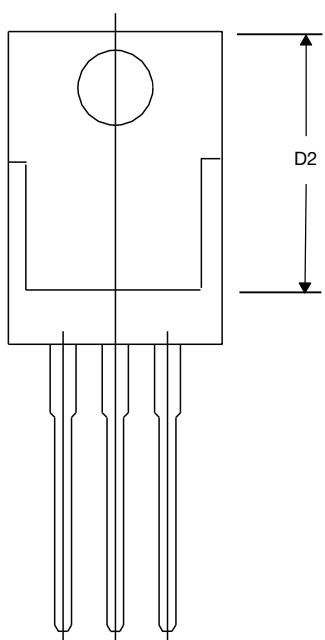


DIM.	MILLIMETERS		INCHES	
	MIN.	MAX.	MIN.	MAX.
A	4.25	4.65	0.167	0.183
b	0.69	1.01	0.027	0.040
b(1)	1.20	1.73	0.047	0.068
c	0.36	0.61	0.014	0.024
D	14.85	15.49	0.585	0.610
D2	12.19	12.70	0.480	0.500
E	10.04	10.51	0.395	0.414
e	2.41	2.67	0.095	0.105
e(1)	4.88	5.28	0.192	0.208
F	1.14	1.40	0.045	0.055
H(1)	6.09	6.48	0.240	0.255
J(1)	2.41	2.92	0.095	0.115
L	13.35	14.02	0.526	0.552
L(1)	3.32	3.82	0.131	0.150
Ø P	3.54	3.94	0.139	0.155
Q	2.60	3.00	0.102	0.118

ECN: T14-0413-Rev. P, 16-Jun-14
DWG: 5471

Note

* M = 1.32 mm to 1.62 mm (dimension including protrusion)
Heatsink hole for HVM



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